


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	ADG/18/11016	
1.3 Title of PCN	PowerFLAT™ 8x8 HV New Die Attach process & material from Power Glue to Solder Paste - ASE-WEIHAI (China)	
1.4 Product Category	Power MOSFET	
1.5 Issue date	2018-07-25	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Maurizio GIUDICE
2.1.2 Marketing Manager	Paolo PETRALI
2.1.3 Quality Manager	Vincenzo MILITANO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New Indirect material part number (same supplier or different supplier): Solder ball composition	ASE-WEIHAI (China)

4. Description of change

	Old	New
4.1 Description	Selected products in PowerFLAT™ 8x8 HV, are manufactured by ASE-WEIHAI (China) Subcontractor with Power Glue in the Die Attach Process.	Selected products in PowerFLAT™ 8x8 HV, are manufactured by ASE-WEIHAI (China) Subcontractor with Solder Paste in the Die Attach Process.
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	no impacts	

5. Reason / motivation for change

5.1 Motivation	Improve Quality
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	will be identified by the additional info "P" marked on the package and internal code reported in the Box Label of the packing.
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7. Timing / schedule

7.1 Date of qualification results	2018-07-18
7.2 Intended start of delivery	2018-10-28
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	11016 Rel14-18.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2018-07-25

9. Attachments (additional documentations)

11016 Public product.pdf
11016 PowerFLAT™ 8x8 HV New Die Attach process & material from Power Glue to Solder Paste.pdf
11016 Rel14-18.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STL23NM60ND	
	STL33N60DM2	
	STL33N60M2	
	STL33N65M2	
	STL36N55M5	
	STL38N65M5	
	STL45N65M5	
	STL57N65M5	



Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : PowerFLAT™ 8x8 HV New Die Attach process & material from Power Glue to Solder Paste - ASE-WEIHAI (China)

PCN Reference : ADG/18/11016

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STL45N65M5	STL57N65M5	STL38N65M5
STL33N60M2	STL36N55M5	STL26NM60N
STL33N60DM2	STL33N65M2	



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